

POSITIVE PHOTSENSITIVE RESIN COMPOSITION, CURED FILM FORMED
BY CURING SAME, AND OPTICAL DEVICE EQUIPPED WITH SAME

Abstract

The purpose of the present invention is to develop a positive photosensitive resin composition which, without compromising high refractive index and high transparency characteristics, has excellent solvent resistance and resolution after pattern formation, and has high sensitivity to exposure, even after long-term storage at room temperature. This positive photosensitive resin composition is characterised by containing: (a) a polysiloxane synthesised by hydrolysing and partially condensing a specific organosilane and an organosilane that has a carboxyl group and/or a dicarboxylic acid anhydride structure; (b) particles of one or more metal compounds selected from an aluminium compound, a tin compound, a titanium compound, and a zirconium compound, or composite particles of a silicon compound and one or more metal compounds selected from an aluminium compound, a tin compound, a titanium compound, and a zirconium compound; (c) a naphthoquinone diazide compound; and (d) a solvent.